



Product Change Notification / GBNG-25TTEO221

Date:

06-Jun-2022

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4664 Final Notice: Qualification of UAT as a new bumping facility and UNIS as a new assembly site for selected 24AAxxx and 11AAxxx device families available in 4L, 5L and 8L CSP packages.

Affected CPNs:

[GBNG-25TTEO221_Affected_CPN_06062022.pdf](#)
[GBNG-25TTEO221_Affected_CPN_06062022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of UAT as a new bumping facility and UNIS as a new assembly site for selected 24AAxxx and 11AAxxx device families available in 4L, 5L and 8L CSP packages.

Pre and Post Change Summary:

	Pre Change	Post Change
Bumping facility	FlipChip International (FCI)	Unisem Advance Tech (UAT)

Assembly Site		Unisem (M) Berhad Perak, Malaysia (UNIS)
Solder Ball Material	SAC266	SNAC105
Polymer Thickness	4.5 um	7 um
UBM Thickness	Al-NiV-Cu (0.4/0.345/0.835) um	0.1um Ti (sp.) + 0.2um Cu(sp.) + 8.6um Cu (pl.)
UBM and RDL Deposition Method	Sputter	Sputter + plated
RDL Thickness	Ti-Al-Ti (0.1/1.8/0.1) um	0.1um Ti (sp.) + 0.2um Cu(sp.) + 4um Cu (pl.)
Backside Coating (BSC) Material	LC2850	LC2826H
Backside Coating (BSC) Thickness	40 um	25 um

Impacts to Data Sheet:Yes. Slight modifications to POD (Package Outline Drawing)

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying UAT as a new bumping facility and UNIS as a new assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:June 13, 2022 (date code: 2225)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	December 2021					->	June 2022				
Workweek	4 9	5 0	5 1	5 2	5 3		2 3	2 4	2 5	2 6	2 7
Initial PCN Issue Date			x								
Qual Report Availability							x				
Final PCN Issue Date							x				

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

December 17, 2021: Issued initial notification.

June 6, 2022: Issued final notification. Attached is the qualification report. Provided estimated first ship date on June 13, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_GBNG-25TTEO221_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

24AA64T-I/CS16K
24AA512T-I/CS17K
24AA256T-I/CS16K
11AA020T-I/CS16K
11AA160T-I/CS16K